ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® MALECTRONICS INDUSTRIES®	PC, Bannockt	ourn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declar he declaration	ation of the n encompass	substance ses all low	s within the er level mat	manufacture erials for wh	er listed ite hich the ma	m. Note: nufacture	if the item is an as er has engineering	ssembly with low responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribut				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
Supplier Information														
Company name*			Company unique ID			Unique ID Authority					Response Date*			
nsemi										2025-05-09				
ntact Name Title - Contact				Phone - Contact*						Email - Contact*				
Product-Env-Stewards Product Envir			Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorized Representative* Title - Representative			sentative	Phone -			Representative*			Email - Representative*				
Product-Env-Stewards Product Enviro Compl			ro Compliance	ompliance NA			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item	Number Mfr Item Name				Effective Da	te Versio	n	Manufacturing Site		W	eight*	UOM	Unit Type
	NRVTS	NRVTSA4100ET3G 4A, 100V Low Le RECTIFIER		eakage TRENC	СН	2025-05-09			VN5		76	6.66	mg	Each
Ianufacturing Proccess Informa	tion													
Terminal Plating / Grid Array Ma	al Plating / Grid Array Material Terminal Base Alloy		Alloy	J-STD-020 MSI	L Rating	Peak Pr	ocess Body	Temperat	ire Max Ti	me at Peak '	Temperatu	e Num	ber of Reflow Cy	cles
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30		second	3			
omments														
vel 1 - maximum time at peak temperatu	re during sol	ldering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the				
Supplier Digital Signature	astislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	7.0	mg	Supplier	Zinc (Zn)	7440-66-6		0.014	mg
			В	Nickel (Ni)	7440-02-0		0.0252	mg
			Supplier	Iron (Fe)	7439-89-6		0.1778	mg
			Supplier	Copper (Cu)	7440-50-8		6.7725	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0105	mg
Die	1.12	mg	Supplier	Silicon (Si)	7440-21-3		1.12	mg
Die Attach Solder	3.45	mg	Supplier	Silver (Ag)	7440-22-4		0.0862	mg
			А	Lead (Pb)	7439-92-1	7a	3.1913	mg
			Supplier	Tin (Sn)	7440-31-5		0.1725	mg
Lead Frame	28.84	mg	Supplier	Zinc (Zn)	7440-66-6		0.0346	mg
			Supplier	Iron (Fe)	7439-89-6		0.6922	mg
			Supplier	Copper (Cu)	7440-50-8		28.0902	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0231	mg
Mold Compound-Black	34.87	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		3.487	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1743	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		5.0561	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		22.6655	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.487	mg
Plating	1.38	mg	Supplier	Tin (Sn)	7440-31-5		1.38	mg